CHIPQUIK® IPC-TEST-FLUX-1-DRY

Datasheet revision 1.1 www.chipquik.com

Solderability Testing Flux # 1 for Tin/Lead Solder IPC J-STD-002 Dry Powder - Makes 19ml with 15ml of IPA (IPA not included)

Product Highlights

RMA Liquid Flux Dry Powder
Isopropyl Alcohol (IPA) not included, needs to be added
Solderability Testing Flux for Tin/Lead Solder
IPC J-STD-002, Flux #1
RoHS 3 and REACH compliant

Liquid Flux shown after 15ml of Isopropyl Alcohol (IPA) has been added to the powdered rosin. IPA is not included.

Specifications

Meets IPC J-STD-002 for Flux #1:
3.2.2 Flux The flux for tin/lead solderability tests shall be a standard activated rosin flux #1 having a composition of 25% +/- 0.5% by weight of colophony and 0.15% +/- 0.01% by weight diethylammonium hydrochloride (CAS 660-68-4), in 74.85% +/- 0.5% by weight of isopropyl alcohol.

Flux Type:	RMA Liquid Flux Dry Powder, Isopropyl Alcohol (IPA) not included, needs to be added. Solderability Testing Flux for Tin/Lead Solder IPC J-STD-002, Flux #1
Flux Classification:	ROL1 (Residue is Non-Corrosive, Non-Conductive)
Specific Gravity:	0.85
Surface Tension:	24-28 mN/m (at 20-25°C)
Dry Net Weight:	4.0g
How much IPA to add:	Add 15ml of IPA. Makes 19ml of Liquid Test Flux #1
Packaging:	1oz Squeeze Bottle
Shelf Life:	Refrigerated >24 months, Unrefrigerated >24 months

Usage Notes

Dry Rosin Powder. User needs to source and add Isopropyl Alcohol (IPA). IPA is not included.
Add 15ml of IPA with included 3ml dropper, close cap, shake well. Allow rosin powder to fully dissolve into IPA before using flux. Makes 19ml of Liquid Test Flux #1.

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). The liquid flux can be allowed to freeze. Freezing will not degrade this product. Allow 4 hours for flux to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product requires ground shipping. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground will not impact this product's stated shelf life.

Cleaning

This is a no-clean liquid flux, post-use cleaning is not required. If cleaning is desired, residue can be cleaned with isopropyl alcohol (IPA), or most other alcohol-based solvent flux removers.

Conforms to the following Industry Standards:

J-STD-002E, Solderability Testing Flux #1:	Yes
J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
RoHS 3 Directive 2015/863/EU:	Yes